

NCE N-Channel Super Trench Power MOSFET

Description

The NCEP40T14G uses **Super Trench** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{DS(ON)}$ and Q_g . This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

General Features

- V_{DS} =40V,I $_{D}$ =140A $R_{DS(ON)}$ =1.6m Ω (typical) @ V_{GS} =10V
- Excellent gate charge x R_{DS(on)} product(FOM)

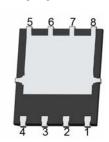
 $R_{DS(ON)}$ =2.3m Ω (typical) @ V_{GS} =4.5V

- Very low on-resistance R_{DS(on)}
- 150 °C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% ΔVds TESTED!

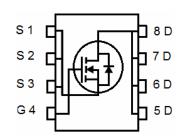
DFN 5X6





Top View

Bottom View



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCEP40T14G	NCEP40T14G	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (T_C=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	40	V
Gate-Source Voltage	V _G s	±20	V
Drain Current-Continuous (Silicon Limited)	I _D	140	Α
Drain Current-Continuous(T _C =100℃)	I _D (100℃)	99	А
Pulsed Drain Current (Package Limited)	I _{DM}	400	А
Maximum Power Dissipation	P _D	133	W
Derating factor		1.06	W/℃
Single pulse avalanche energy (Note 5)	Eas	980	mJ
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}\!\mathbb{C}$

Thermal Characteristic

Thermal Resistance,Junction-to-Case ^(Note 2)	$R_{ heta JC}$	0.94	°C/W
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Electrical Characteristics (T_C=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	40		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =40V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20V, V_{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	1.0	1.5	2.0	V
Drain-Source On-State Resistance	Б	V _{GS} =10V, I _D =20A	-	1.6	1.9	mΩ
Diani-Source On-State Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =20A	-	2.3	2.65	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =20A		75	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ -20\/\/ -0\/	-	5000	-	PF
Output Capacitance	Coss	$V_{DS}=20V, V_{GS}=0V,$	-	1950	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	110	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	12	-	nS
Turn-on Rise Time	t _r	V_{DD} =20 V , I_{D} =20 A	-	6.5	-	nS
Turn-Off Delay Time	$t_{d(off)}$	V_{GS} =10 V , R_{G} =1.6 Ω	-	49	-	nS
Turn-Off Fall Time	t _f		-	8	-	nS
Total Gate Charge	Qg	V -20VI -20A	-	90	-	nC
Gate-Source Charge	Q _{gs}	$V_{DS}=20V,I_{D}=20A,$	-	17	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} =10V	-	14	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V _{GS} =0V,I _S =20A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	140	Α
Reverse Recovery Time	t _{rr}	$T_J = 25^{\circ}C, I_F = I_S$	-	24	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	85	-	nC
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Notes:

- ${\bf 1.}\ {\bf Repetitive}\ {\bf Rating:}\ {\bf Pulse}\ {\bf width}\ {\bf limited}\ {\bf by}\ {\bf maximum}\ {\bf junction}\ {\bf temperature}.$
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,VDD=20V,VG=10V,L=0.5mH,Rg=25 Ω



Typical Electrical and Thermal Characteristics

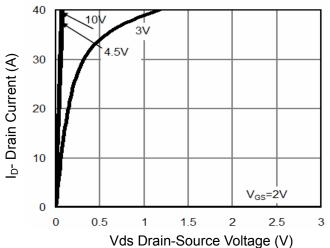


Figure 1 Output Characteristics

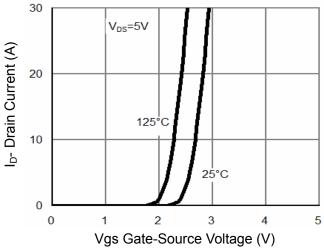


Figure 2 Transfer Characteristics

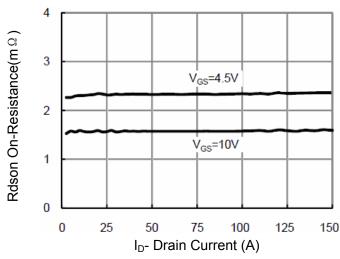


Figure 3 Rdson- Drain Current

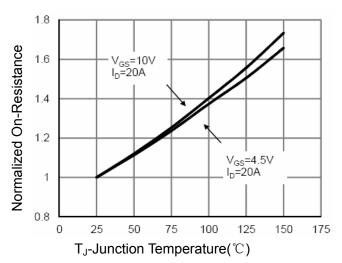


Figure 4 Rdson-JunctionTemperature

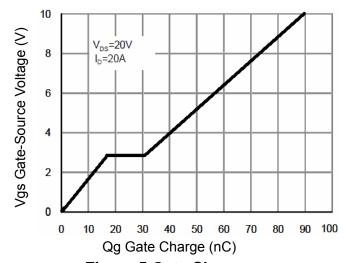


Figure 5 Gate Charge

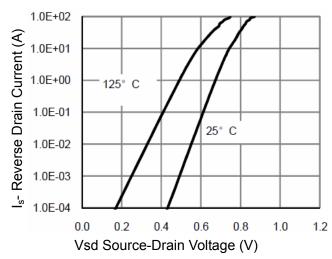


Figure 6 Source- Drain Diode Forward



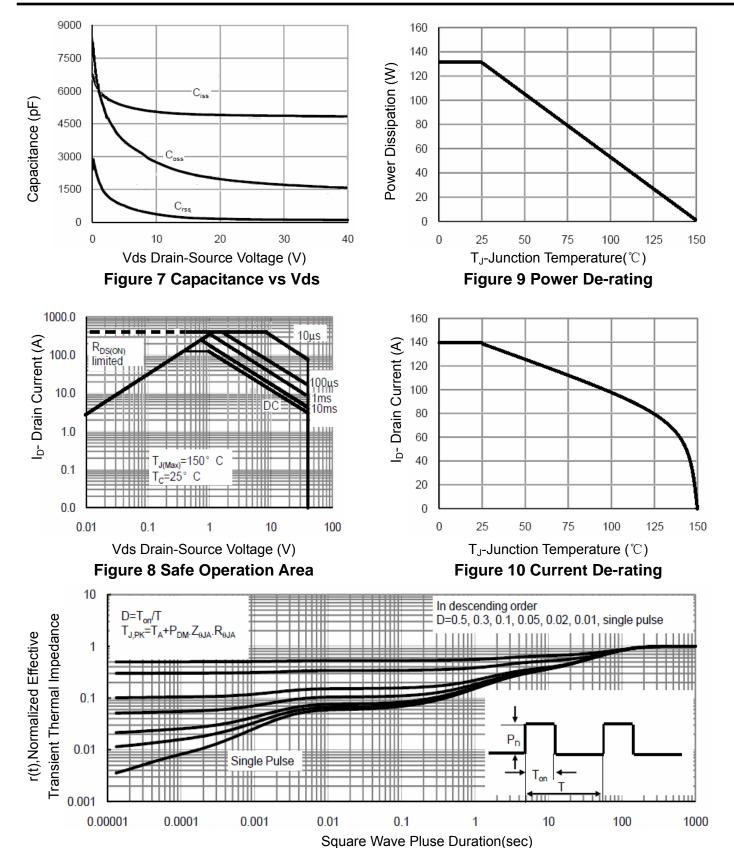
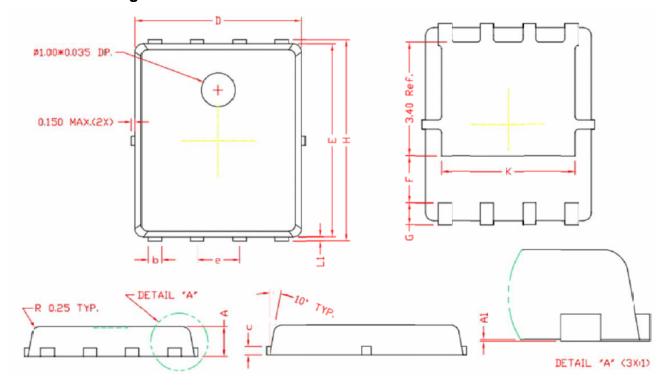


Figure 11 Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX		
A	0.80	0.90	1.00		
A1	0.00	0.03	0.05		
b	0.35	0.42	0.49		
С	0. 254 REF.				
D	4.90	5.00	5. 10		
F	1.40 REF.				
E	5.70	5.80	5.90		
е	1.27 BSC.				
Н	5.95	6.08	6. 20		
L1	L1 0.10		0.18		
G	0.60 REF. 4.00 REF.				
K					





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